

BOM Change Summary

▶ ASDP-BF33 and ADSP-BF533L (19x19_MM)

Assembly Site	STATS Singapore - STA (From)	STATS Korea – SK3 (To)
Wire	Au / 1.0 mil	Au / 1.0 mil
Die Attach	Ablestik 2000 conductive	Ablestik 2000B conductive
Mold Compound	Sumitomo G770	Sumitomo G760SYA (Low Alpha)
Ball Size	0.6	0.6
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu
Plating	100Sn	100Sn

BOM Change Summary

▶ ASDP-TS101S (19x19_MM)

Assembly Site	STATS Singapore - STA (From)	STATS Korea – SK3 (To)
Wire	Au / 1.2 mil	Au / 1.2 mil
Die Attach	Ablestik 2000 conductive	Ablestik 2000B conductive
Mold Compound	Sumitomo G770	Sumitomo G760SYA (Low Alpha)
Ball Size	0.50	0.50
Ball Composition	96.5Sn_3.0Ag_0.5Cu	96.5Sn_3.0Ag_0.5Cu
Plating	100Sn	100Sn